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Applicant(s): Liang et al.

Docket No.

PHNL000195

Serial No.  
09/829,797Filing Date  
04/10/2001Examiner  
LewisGroup Art Unit  
2822

Invention: SEMICONDUCTOR DEVICE WITH ISOLATED INTERMETAL DIELECTRICS

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Liang et al.

Examiner: Lewis

Application No.: 09/829,797

Art Unit: 2822

Filed: April 10, 2001

For: SEMICONDUCTOR DEVICE WITH ISOLATED INTERMETAL DIELECTRICS

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Box AF  
Commissioner for Patents  
Washington D.C. 20231AMENDMENT

Sir:

In response to the final Office Action of September 26, 2002, Applicants respectfully request that the above-identified application be reconsidered in view of the amendments and remarks that follow, and that the application be passed to issue.

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In the Claims

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Please amend the claims as follows:

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1. (AMENDED) A semiconductor device comprising a bond pad structure, which bond pad structure comprises a bond pad disposed above at least one layered structure, wherein the layered structure comprises a metal layer and a layer of dielectric material, characterized in that via lines are present in the layer of a dielectric material, which via lines are connected to the metal layer to form isolated areas filled with dielectric material.

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